

Product List

MSU2032L16, low working voltage 16 MHz ROM less MCU

MSU2032C16, 16 MHz ROM less MCU

MSU2032C25, 25 MHz ROM less MCU

MSU2032C40, 40 MHz ROM less MCU

MSU2052L16, low working voltage 16 MHz 4 KB internal ROM MCU

MSU2052C16, 16 MHz 4 KB internal ROM MCU

MSU2052C25, 25 MHz 4 KB internal ROM MCU

MSU2052C40, 40 MHz 4 KB internal ROM MCU

Description

The MVI MSU2052 series product is an 8 - bit single chip microcontroller. It provides hardware features and a powerful instruction set, necessary to make it a versatile and cost effective controller for those applications demand up to 32 I/O pins or need up to 64 K byte external memory either for program or for data or mixed. A serial input / output port is provided for I/O expansion, Inter - processor communications, and full duplex UART.

Ordering Information

MSU2032ihhk

MSU2052ihh - yyyk

i: process identifier {L, C}.

hh: working clock in MHz {16, 25, 40}.

yyy: production code {001, ..., 999}

k: package type postfix {as below table}.

Postfix	Package	Pin/Pad Configuration	Dimension	Logo Size at Top Marking
blank	dice	page 18	page 18	-
P	40L P DIP	page 2	page 14	5.0 x 4.2 mm
J	44L P LCC	page 2	page 15	4.5 x 3.8 mm
Q	44L P QFP	page 2	page 16	2.8 x 2.4 mm
U	44L L QFP	page 2	page 17	2.8 x 2.4 mm

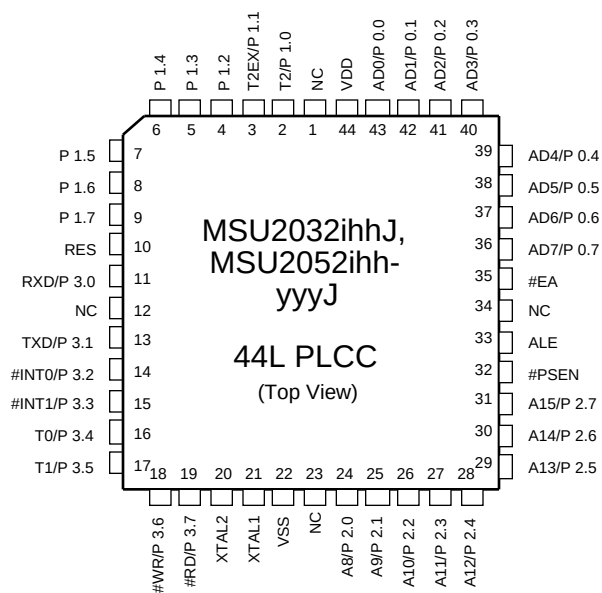
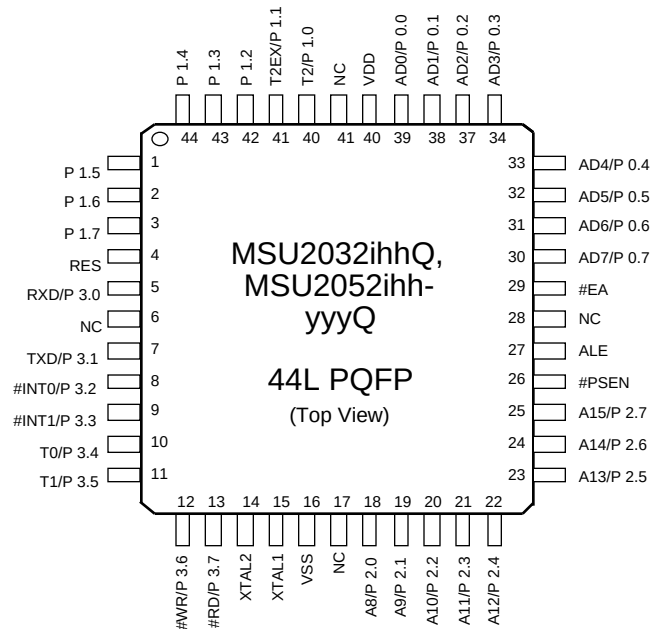
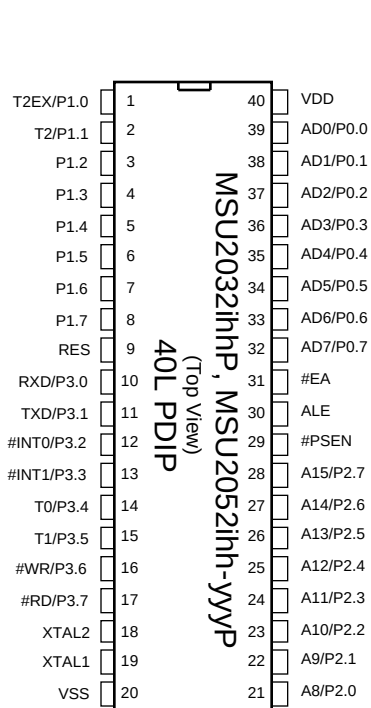
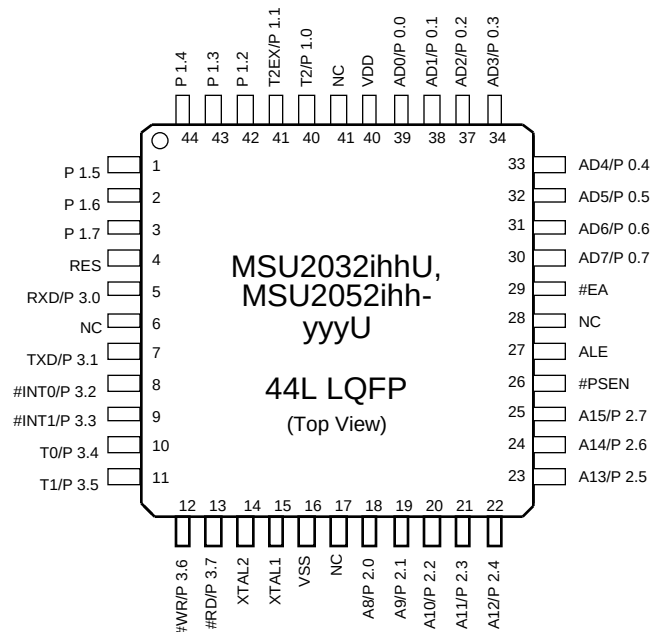
Features

- Working voltage : L series at 2.7V through 4.5V while S & C series at 4.5 V through 5.5 V
- General 80C51 family compatible
- 64 K byte External Memory Space
- 8 K byte ROM
- 256 byte data RAM
- Three 16 bit Timers/Counters
- Four 8-bit I/O ports
- Full duplex serial channel
- Bit operation instructions
- Page free jumps
- 8 - bit Unsigned Division
- 8 - bit Unsigned Multiply
- BCD arithmetic
- Direct Addressing
- Indirect Addressing
- Nested Interrupt
- Two priority level interrupt
- A serial I/O port
- Power save modes:
Idle mode and Power down mode
- Working at 16/25/40 MHz Clock

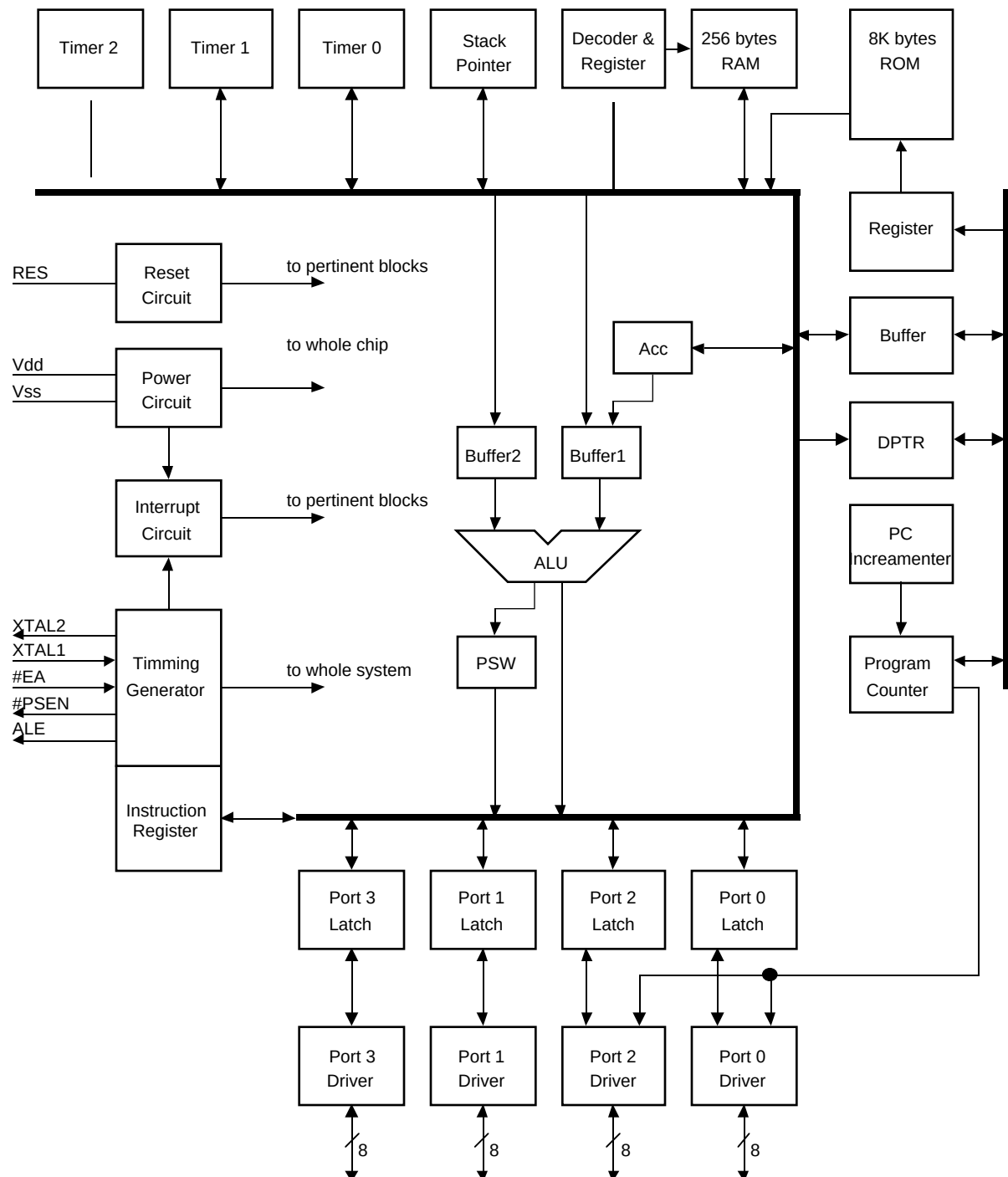
Cross Reference

M.V.I.	MSU2052	MSU2032
W.B.	W78C52	W78C32
Philips	80C52	80C32
L.G.	GMS80C502	GMS80C302
Intel	80C52	80C32
CCL. itri	CIC80520	- - - -
Atmel	AT80C52	AT80C32

Pin Configurations



Block Diagram



Pin Descriptions

40 PDIP Pin#	Dice Pad#	44 LQFP Pin#	44 PQFP Pin#	44 PLCC Pin#	Symbol	Active	I/O	Names
1	39	40	40	2	T2EX/P1.0		i/o	bit 0 of Port 1 & timer 2
2	40	41	41	3	T2/P1.1		i/o	bit 1 of Port 1 & timer control
3	41	42	42	4	P1.2		i/o	bit 2 of Port 1
4	42	43	43	5	P1.3		i/o	bit 3 of Port 1
5	43	44	44	6	P1.4		i/o	bit 4 of Port 1
6	1	1	1	7	P1.5		i/o	bit 5 of Port 1
7	2	2	2	8	P1.6		i/o	bit 6 of Port 1
8	3	3	3	9	P1.7		i/o	bit 7 of Port 1
9	4	4	4	10	RES		i	Reset
10	5	5	5	11	RXD/P3.0		i/o	bit 0 of Port 3 & Receive data
11	6	7	7	13	TXD/P3.1		i/o	bit 1 of Port 3 & Transmit data
12	7	8	8	14	#INT0/P3.2	L/-	i/o	bit 2 of Port 3 & low true Interrupt 0
13	8	9	9	15	#INT1/P3.3	L/-	i/o	bit 3 of Port 3 & low true Interrupt 1
14	9	10	10	16	T0/P3.4		i/o	bit 4 of Port 3 & Timer 0
15	10	11	11	17	T1/P3.5		i/o	bit 5 of Port 3 & Timer 1
16	11	12	12	18	#WR/P3.6	L/-	i/o	bit 6 of Port 3 & Write (low enable)
17	12	13	13	19	#RD/P3.7	L/-	i/o	bit 7 of Port 3 & Read (low enable)
18	13	14	14	20	XTAL2		o	Crystal out
19	14	15	15	21	XTAL1		i	Crystal in
20	15-17	16	16	22	VSS			Sink Voltage, Ground
21	18	18	18	24	A8/P2.0		i/o	bit 0 of Port 2 & Address 8
22	19	19	19	25	A9/P2.1		i/o	bit 1 of Port 2 & Address 9
23	20	20	20	26	A10/P2.2		i/o	bit 2 of Port 2 & Address 10
24	21	21	21	27	A11/P2.3		i/o	bit 3 of Port 2 & Address 11
25	22	22	22	28	A12/P2.4		i/o	bit 4 of Port 2 & Address 12
26	23	23	23	29	A13/P2.5		i/o	bit 5 of Port 2 & Address 13
27	24	24	24	30	A14/P2.6		i/o	bit 6 of Port 2 & Address 14
28	25	25	25	31	A15/P2.7		i/o	bit 7 of Port 2 & Address 15
29	26	26	26	32	#PSEN	L	o	Program store enable (low enable)
30	27	27	27	33	ALE	H	o	Address latch enable
31	28	29	29	35	#EA	L	i	External access first 8 KB memory
32	29	30	30	36	AD7/P0.7		i/o	bit 7 of Port 0 & Address or Data 7
33	30	31	31	37	AD6/P0.6		i/o	bit 6 of Port 0 & Address or Data 6
34	31	32	32	38	AD5/P0.5		i/o	bit 5 of Port 0 & Address or Data 5
35	32	33	33	39	AD4/P0.4		i/o	bit 4 of Port 0 & Address or Data 4
36	33	34	34	40	AD3/P0.3		i/o	bit 3 of Port 0 & Address or Data 3
37	34	35	35	41	AD2/P0.2		i/o	bit 2 of Port 0 & Address or Data 2
38	35	36	36	42	AD1/P0.1		i/o	bit 1 of Port 0 & Address or Data 1
39	36	37	37	43	AD0/P0.0		i/o	bit 0 of Port 0 & Address or Data 0
40	37,38	38	38	44	VDD			Drive Voltage, +3 Vcc (or +5 Vcc)

Pin Descriptions**Vss**

Circuit ground potential.

VDD

+3V (or +5 V) power supply during operation.

PORT 0

Port 0 is an 8-bit open drain bidirectional I/O port. It is also the multiplexed low-order address and data bus when using external memory. It also contains the timer 2 & its control pins.

PORT 1

Port 1 is an 8-bit quasi-bidirectional I/O port with internal pull-up resistance.

PORT 2

Port 2 is an 8-bit quasi-bidirectional I/O port with internal pull-up resistance. It also emit the high-order address byte when accessing external memory.

PORT 3

Port 3 is an 8-bit quasi-bidirectional I/O port with internal pull-up resistance. It also contains the interrupt, timer, serial port and #RD as well as #WR pins that are used by various options. The output latch corresponding to a secondary function must be programmed to one (1) for that function to operate. The secondary functions are assigned to the pins of port 3, as follows:

- RXD/data (P3.0). Serial port's transmitter data output (asynchronous) or data input/output (asynchronous).
- TXD/clock (P3.1). Serial port's transmitter data output (asynchronous) or data output (asynchronous).
- #INT0 (P3.2). Interrupt 0 input or gate control input for counter 0.
- #INT1 (P3.3). Interrupt 1 input or gate control input for counter 1.
- T0 (P3.4). Input to counter 0.
- T1 (P3.4). Input to counter 1.
- #WR (P3.6). The write control signal latches the data byte from Port 0 into the External Data Memory.
- #RD (P3.7). The read control signal enables External Data Memory to Port 0.

RES

A high on this pin for two machine cycles (24 clocks) while the oscillator is running, resets the device. The data in RAM is preserved when reset signals - reset does not clear the data in RAM.

ALE

Provides Address Latch Enable output used for latching the address into external memory during normal operation.

#PSEN

The Program Store Enable output is a control signal that enables the external Program Memory to the bus during normal fetch operations.

#EA

When held at a TTL high level, the MSU2052 executes instructions from the internal ROM when the PC is less than 4096. When held at a TTL low level, the MSU2052 fetches all instructions from external Program Memory.

XTAL 1

Input to the oscillator's high gain amplifier. A crystal or external source can be used.

XTAL 2

Output from the oscillator's amplifier. Required when a crystal is used.

Terms**Idle Mode**

During idle mode, the CPU is stopped but below blocks are kept functioning: clock generator, RAM, timer/counters, serial port and interrupt block. To save power consumption, user's software program can invoke this mode. The on-chip data RAM retains the values during this mode, but the processor stops executing instructions. In Idle mode (IDL=1), the oscillator continues to run and the interrupt, and timer blocks continue to be clocked but the clock signal is gated off to the CPU. The activities of the CPU no longer exist unless waiting for an interrupt request.

-An instruction that sets flag (PCON.0) causes that to be the last instruction executed before going into the Idle Mode.

-In the Idle Mode, the internal clock signal is gated off to the CPU, but not to the interrupt, Timer function.

-The CPU status is entirely preserved in its: the Stack Pointer, Program Counter, Program Status Word, Accumulator, and all other registers maintain their data during Idle mode.

-There are three ways to terminate the Idle Mode.

1) By interrupt

Activation of any enabled interrupt will cause flag (PCON.0) to be cleared by hardware, termination the Idle Mode. After the program wakes up, the PC value will point as interrupt vector (if enable IE register) and execute interrupt service routine then return to PC+1 address after the program wakes up.

2) By hardware reset

Since the clock oscillator is still running, the hardware reset needs to be held active for only two machine cycles (24 oscillator periods) to complete the reset. All SFR and PC value will be cleared to reset value.

3) By one of CLK, DATA, PORT 2.0-2.7 transition to low (falling edge trigger)

After the program wakes up, the PC value will be 0023h (if enable IE register) and execute interrupt service routine and then returns to PC+1 address after the program wakes up.

Power Down Mode

It saves the RAM content, stops the clock generator and disables every other blocks' function until the coming hardware reset. To save even more power consumption, user's software program can invoke this mode. The SFRs and the on-chip data RAM retain their values during this mode, but the porcessor stops executing instructions. In Power-Down mode (PD=1) the oscillator is frozen.

-An instruction that sets flag (PCON.1) causes that to be the last instruction executed before going into the Power Down Mode.

-In the Power Down Mode, the on-chip oscillator is stopped.

With the clock frozen, all functions are stopped, but the on-chip RAM and Special Function Registers are held.

-Reset redefines all the SFRs, but does not change the on-chip RAM.

-There are two ways to terminate the Power Down Mode.

1) By hardware reset

All SFR and PC value will be cleared to reset value.

2) One of CLK, DATA, PORT 2.0-2.7 transition to low (falling edge trigger)

After the program wakes up, the PC value will be 0023h (if enable IE register) and execute interrupt service routine and then returns to PC+1 address after the program wakes up.

-Care must be taken, however, to ensure that VCC is not reduced before the Power Down Mode is invoked, and that VCC is restored to its normal operating level before the Power Down Mode is terminated.

-The hardware reset must be held active long enough to allow the oscillator to restart and stabilize.

General of above

User should fix the attention on using wake up from port 2:

-The user should write the power down or idle mode flag value to one RAM address before write PCON to distinguish waking up from power down mode or idle mode.

-After idle mode or power down mode wakes up, the interrupt service routine will be executed first and then executes PC+1 address if the IE register is enabled before entering power down mode or idle mode. The interrupt service routine will not be executed but CPU executes PC+1 address program if disable IE register.

-After wake up power down or idle mode the IDF flag will be set by hardware. The IDF flag be cleared at the ISR execution time. If IE register is disable, the IDF flag will not be cleared when power down or idle mode wakes up.

The state of pins during Idle and Power-Down Mode

Mode	Program memory	ALE	#PSEN	Port 0	Port 1	Port 2	Port 3
Idle	Internal	1	1	Data	Data	Data	Data
Idle	External	1	1	Float	Data	Address	Data
Power Down	Internal	0	0	Data	Data	Data	Data
Power Down	External	0	0	Float	Data	Data	Data

Absolute Maximal Rating

Symbol	Name	Rating	Unit	Remark
V _{dd} - V _{ss}	DC supply Voltage	-0.5 ~ +5.0	V	U20x1L
		-0.5 ~ +7.0	V	U20x1S,U20x1C
V _{IN}	Input voltage	V _{ss} -0.3 ~ V _{dd} +0.3	V	
V _{OUT}	output voltage	V _{ss} ~ V _{dd}		
T (Operating)	Operating Temperature	0 ~ +70	°C	
T (Storage)	Storage Temperature	-55 ~ +125	°C	

* Note:
Operation beyond Absolute Maximal Rating can adversely affect device reliability.

Operating Conditions

Symbol	Description	Min.	Typ.	Max.	Unit	Remarks
t _A	Ambient temperature under bias	0	25	70	C	
V _{CC3}	Supply voltage	2.7	3.0	4.5	V	U20x2L
V _{CC5}		4.5	5.0	5.5	V	U20x2C
f _{osc 16}	Oscillator Frequency	3.0	16	16	MHz	U20x2i16
f _{osc 25}		16	25	25	MHz	U20x2i25
f _{osc 40}		25	40	40	MHz	U20x2i40

AC Characteristics

(16/25/40 MHz, operating conditions; CL for Port 0, ALE and PSEN Outputs=150pF; CL for all Other Outputs=80pF)

Symbol	Parameter	Valid Cycle	f _{osc 16}			Variable f _{osc}			Unit	Remarks
			Min.	Typ.	Max	Min.	Typ.	Max.		
T _{LHLL}	ALE pulse width	RD/WRT	115			2xT - 10			nS	
T _{AVLL}	Address Valid to ALE low	RD/WRT	43			T - 20			nS	
T _{LLAX}	Address Hold after ALE low	RD/WRT	53			T - 10			nS	
T _{LLIV}	ALE low to Valid Instruction In	RD			240			4xT - 10	nS	
T _{LLPL}	ALE low to #PSEN low	RD	53			T - 10			nS	
T _{PLPH}	#PSEN pulse width	RD	173			3xT - 15			nS	
T _{PLIV}	#PSEN low to Valid Instruction In	RD			177			3xT - 10	nS	
T _{PXIX}	Instruction Hold after #PSEN	RD	0			0			nS	
T _{PXIZ}	Instruction Float after #PSEN	RD			87			T + 25	nS	
T _{AVIV}	Address to Valid Instruction In	RD			292			5xT - 20	nS	
T _{PLAZ}	#PSEN low to Address Float	RD			10			10	nS	
T _{RLRH}	#RD pulse width	RD	365			6xT - 10			nS	
T _{WLWH}	#WR pulse width	WRT	365			6xT - 10			nS	
T _{RLDV}	#RD low to Valid Data In	RD			302			5xT - 10	nS	
T _{RHDX}	Data Hold after #RD	RD	0			0			nS	
T _{RHDZ}	Data Float after #RD	RD			145			2xT + 20	nS	
T _{LLDV}	ALE low to Valid Data In	RD			490			8xT - 10	nS	
T _{AVDV}	Address to Valid Data In	RD			542			9xT - 20	nS	
T _{LLYL}	ALE low to #WR or #RD low	RD/WRT	178		197	3xT - 10		3xT + 10	nS	
T _{AVYL}	Address Valid to #WR or #RD low	RD/WRT	230			4xT - 20			nS	
T _{QVWH}	Data Valid to #WR High	WRT	403			7xT - 35			nS	
T _{QVWX}	Data Valid to #WR transition	WRT	38			T - 25			nS	
T _{WHQX}	Data hold after #WR	WRT	73			T + 10			nS	
T _{RLAZ}	#RD low to Address Float	RD						5	nS	
T _{YHLH}	#WR or #RD high to ALE high	RD/WRT	53		72	T - 10		T + 10	nS	
T _{CHCL}	Clock fall time								nS	
T _{CLCX}	Clock low time								nS	
T _{CLCH}	Clock rise time								nS	
T _{CHCX}	Clock high time								nS	
T, T _{CLCL}	Clock period			63			1/ fosc		nS	

DC Characteristics

(16/25/40 MHz, typical operating conditons, valid for U20x2C series)

Symbol	Parameter	Valid	Min.	Typ.	Max	Unit	Test Conditions
V ILX	Input Low Voltage	XTAL1	-0.5		20%Vcc-0.1	V	
V ILE	"	#EA	0		20%Vcc-0.3	V	
V ILR	"	RES	-0.5		20%Vcc-0.1	V	
V IHX	Input High Voltage	XTAL1	70%Vcc		Vcc+0.5	V	
V IHE	"	#EA	20%Vcc+0.9		Vcc+0.5	V	
V IHR	"	RES	70%Vcc		Vcc+0.5	V	
V OLA	Output Low Voltage	ALE, #PSEN			450	mV	I OL = 3.2 mA
V OLO	"	ports 0,3			450	mV	I OL = 3.2 mA
V OL1	"	ports 1,2			450	mV	I OL = 1.6 mA
V OHA	Output High Voltage	ALE, #PSEN	2.4			V	I OH = -60 uA
	"		90%Vcc			V	I OH = -10 uA
V OH0	"	port 0	2.4			V	I OH = -800 uA
	"		90%Vcc			V	I OH = -80 uA
V OH1	"	ports 1,3	2.4			V	I OH = -60 uA
	"		90%Vcc			V	I OH = -10 uA
V OH2	"	port 2	2.4			V	I OH = -60 uA
	"		90%Vcc			V	I OH = -10 uA
I OLO	Output Low Current	ports 0,3		18		mA	V OL = 0.45V, note 1
I IL	Logical 0 Input Current	ports 1,2,3			-50	uA	V in = 0.45 V
I IH	Logical 1 Input Current	port 0			1.5	uA	V in = 5.0 V
I TL	Logic Transition Current	ports 1,2,3			-650	uA	V in = 2.0 V
I LI	Input Leakage Current	port 0			10	uA	0.45V < V in < Vcc
R RES	Reset Pulldown Resistance	RES	50		150	Kohm	
R X	Crystal feedback Resistance	XTAL1,2	90		330	Kohm	
C IO	Pin Capacitance				10	pF	Freq=1MHz, Ta=25 °C
I CC	Power Supply Current	Vdd		5	8	mA	Active mode, 16 MHz
		Vdd		3	5	mA	Idle mode, 16MHz
		Vdd		10	45	uA	Power down mode

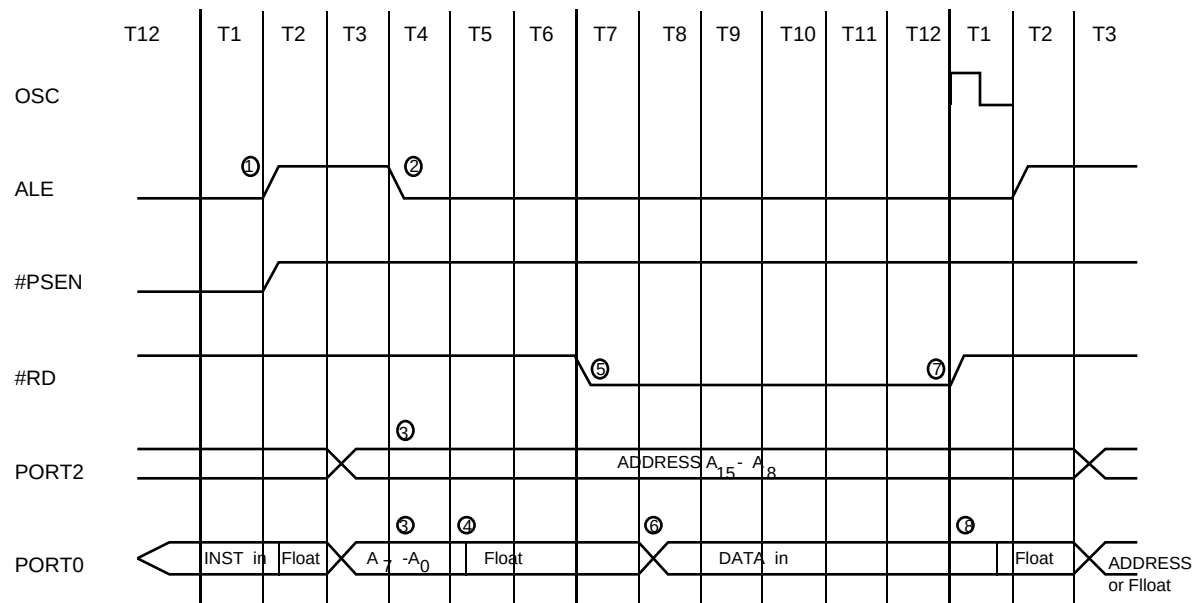
note 1 : no more than 80 mA I OLs for all 16-bit ports 0 & 3 output pins.

DC Characteristics

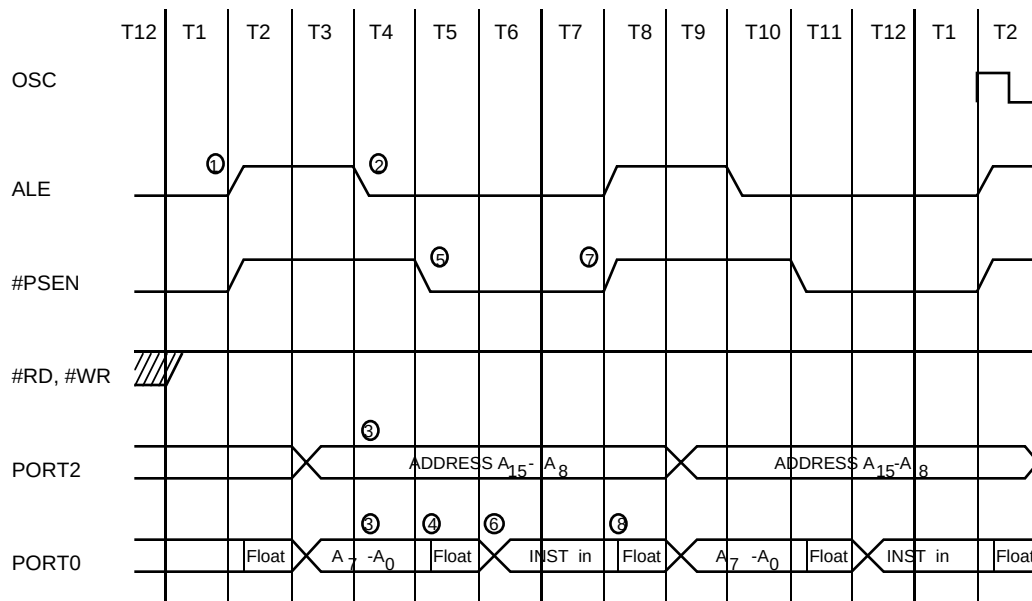
(16 MHz, typical operating conditions, valid for U20x2L series)

Symbol	Parameter	Valid	Min.	Typ.	Max	Unit	Test Conditions
V ILX	Input Low Voltage	XTAL1				mV	
V ILE	"	#EA				mV	
V ILR	"	RES				mV	
V IHX	Input High Voltage	XTAL1			V _{CC} +0.3	V	
V IHE	"	#EA			V _{CC} +0.3	V	
V IHR	"	RES			V _{CC} +0.3	V	
V OLA	Output Low Voltage	ALE, #PSEN			400	mV	I _{OL} = 3.2 mA
V OL0	"	ports 0,3			400	mV	I _{OL} = 3.2 mA
V OL1	"	ports 1,2			400	mV	I _{OL} = 1.6 mA
V OHA	Output High Voltage	ALE, #PSEN	1.8			V	I _{OH} = -60 uA
	"		2.4			V	I _{OH} = -10 uA
V OH0	"	port 0	2.2			V	I _{OH} = -800 uA
	"		2.4			V	I _{OH} = -80 uA
V OH1	"	ports 1,3	1.8			V	I _{OH} = -60 uA
	"		2.4			V	I _{OH} = -10 uA
V OH2	"	port 2	1.8			V	I _{OH} = -60 uA
	"		2.4			V	I _{OH} = -10 uA
I IL	Logical 0 Input Current	ports 1,2,3			45	uA	V _{in} = 0.45 V
I IH	Logical 1 Input Current	port 0			1	uA	V _{in} = 3.0 V
I TL	Logic Transition Current	ports 1,2,3			250	uA	V _{in} = 1.4 V
I LI	Input Leakage Current	port 0			8	uA	0.45V < V _{in} < V _{CC}
R RES	Reset Pulldown Resistance	RES	50		150	Kohm	
R X	Crystal feedback Resistance	XTAL1,2	90		330	Kohm	
C IO	Pin Capacitance				10	pF	Freq=1MHz, T _a =25 °C
I CC	Power Supply Current	V _{DD}		2	7	mA	Active mode, 16 MHz
		V _{DD}		1	4.5	mA	Idle mode, 16MHz
		V _{DD}		10	45	uA	Power down mode

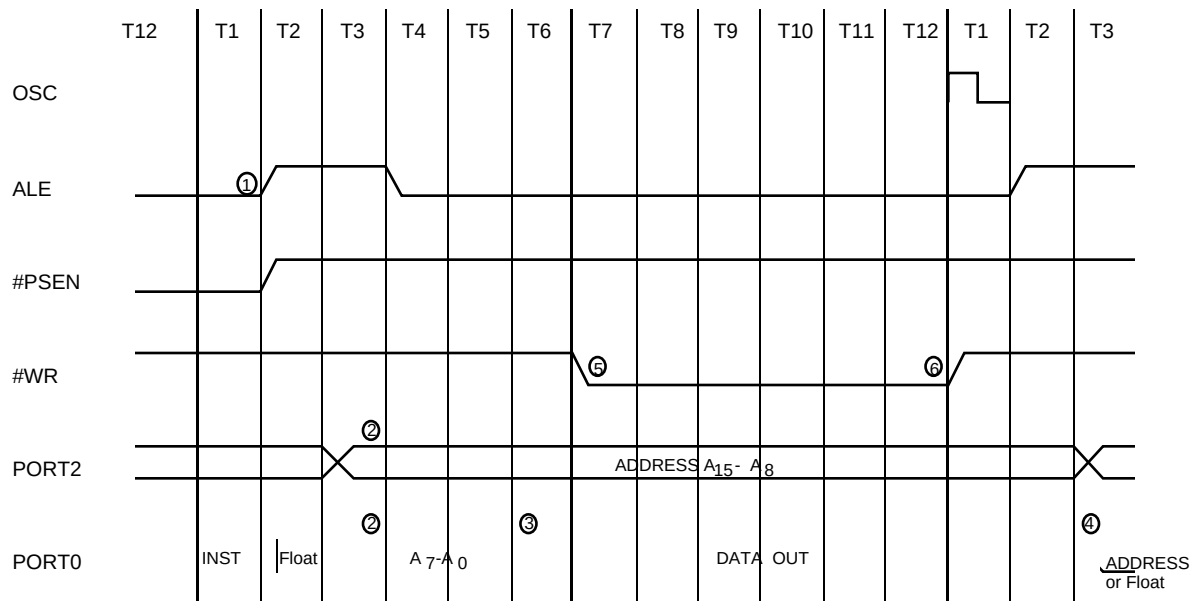
Data Memory Read Cycle Timing



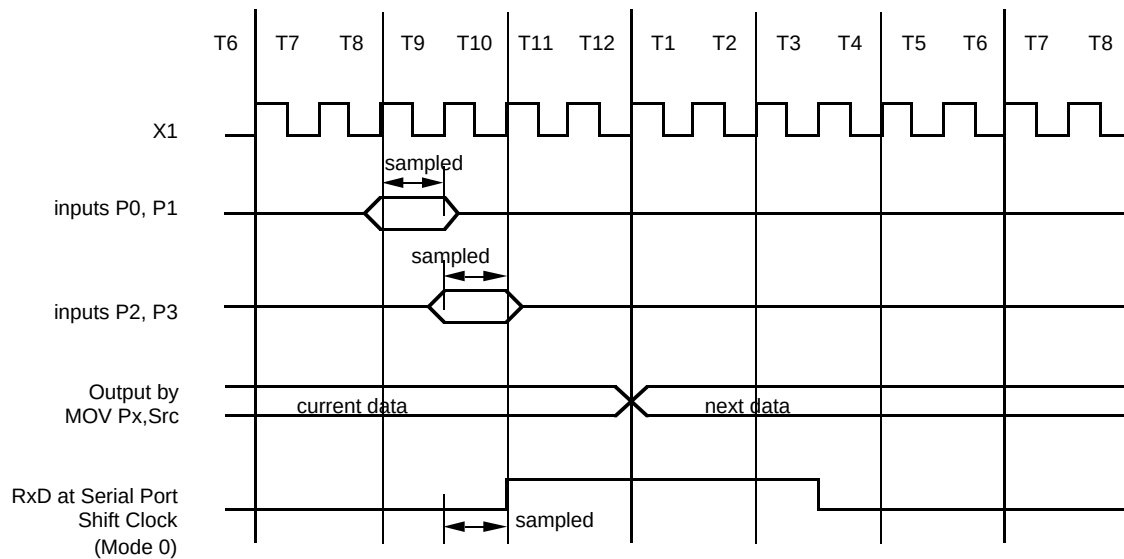
Program Memory Read Cycle Timing

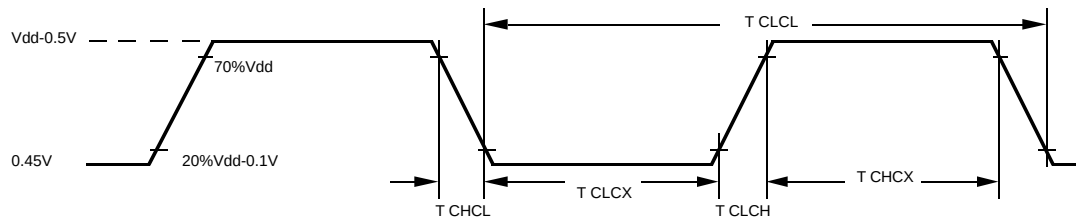
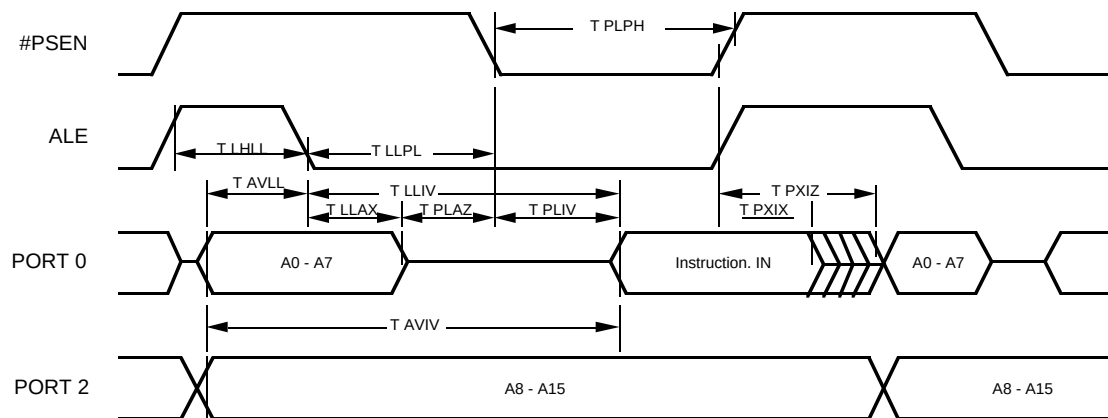
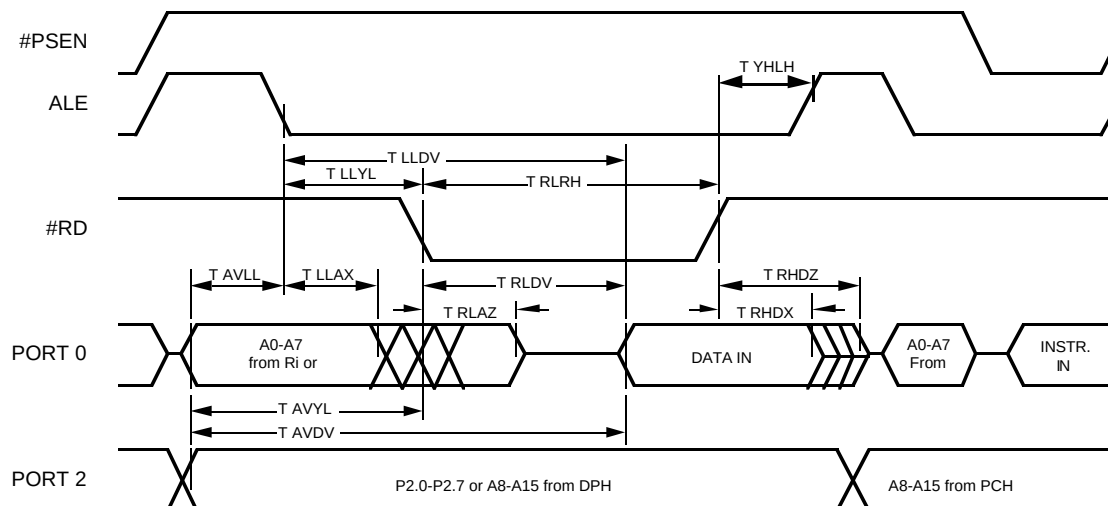


Data Memory Write Cycle Timing

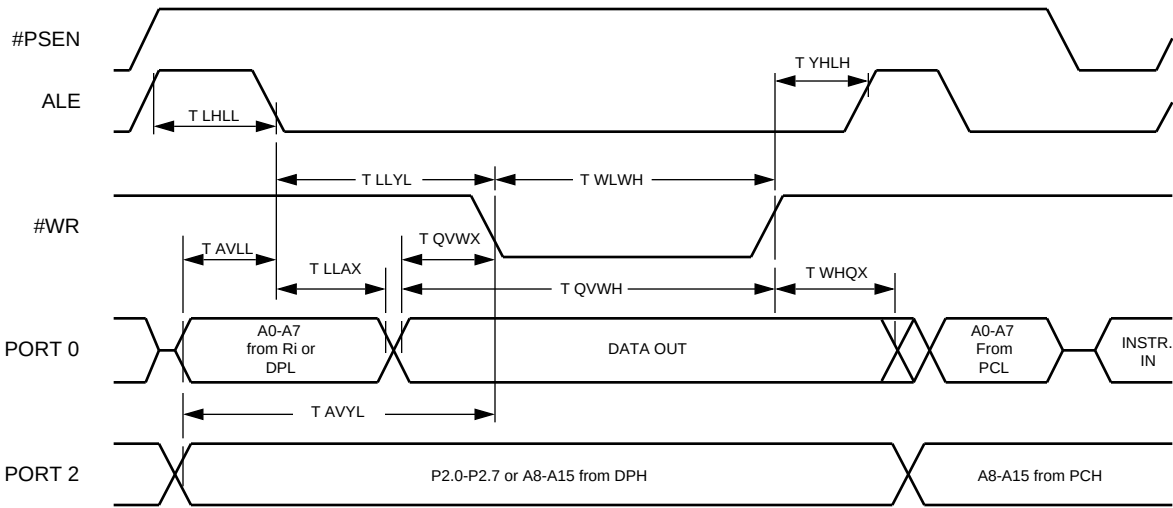


I/O Ports Timing



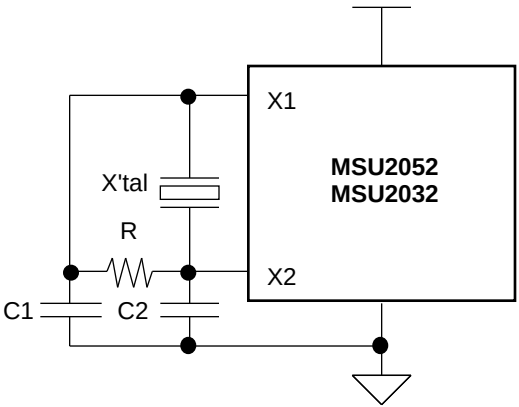
Timing Critical, Requirement of External Clock ($V_{SS}=0.0V$ is assumed)**Tm.I External Program Memory Read Cycle****Tm.II External Data Memory Read Cycle**

Tm.III External Data Memory Write Cycle

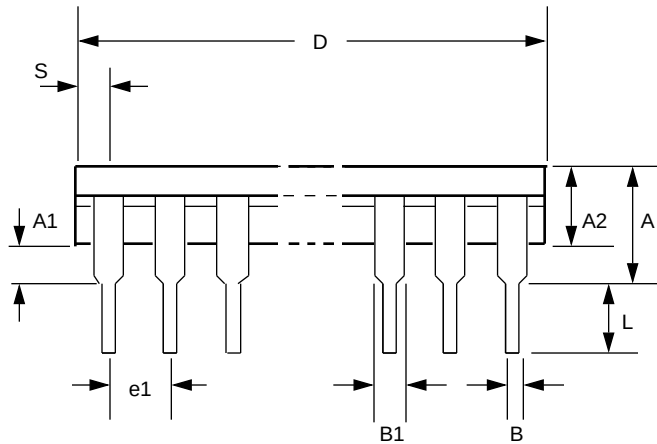
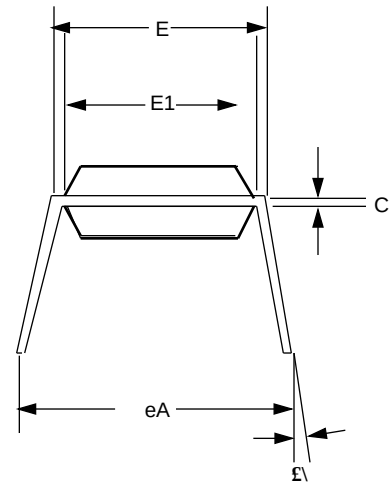


Application Reference

Valid for U2052L16/ U2032L16				
X'tal	3 MHz	6 MHz	12 MHz	16 MHz
C1	15 pF	15 pF	30 pF	30 pF
C2	15 pF	15 pF	30 pF	30 pF
R	open	open	open	open
Valid for U2052C16/ U2032C16/ U2052C25/ U2032C25/ U2052C40/ U2032C40				
X'tal	12 MHz	16 MHz	25 MHz	40 MHz
C1	30 pF	30 pF	15 pF	5 pF
C2	30 pF	30 pF	15 pF	5 pF
R	open	open	62 Kohm	4.7 Kohm



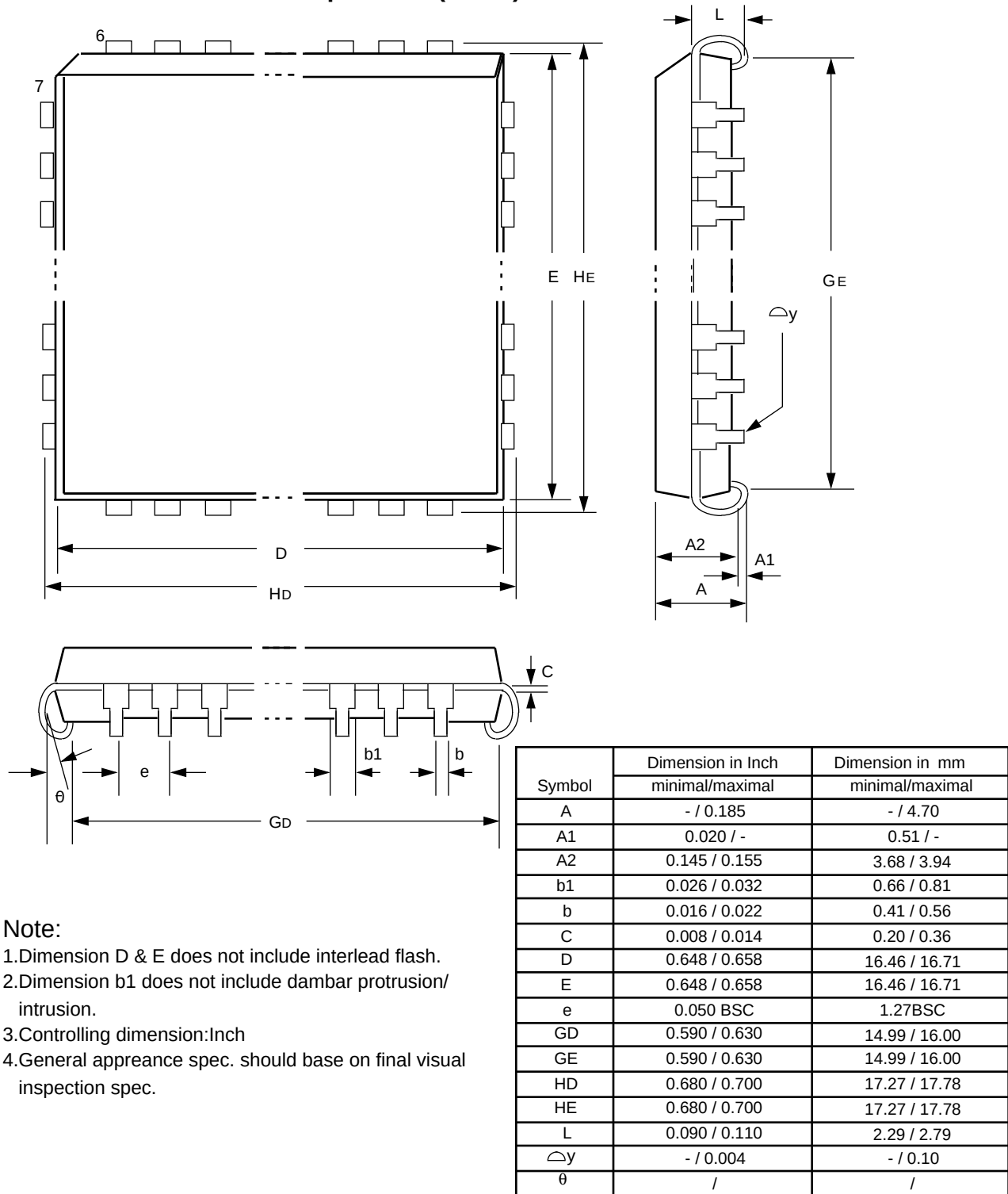
40L 600mil PDIP Information



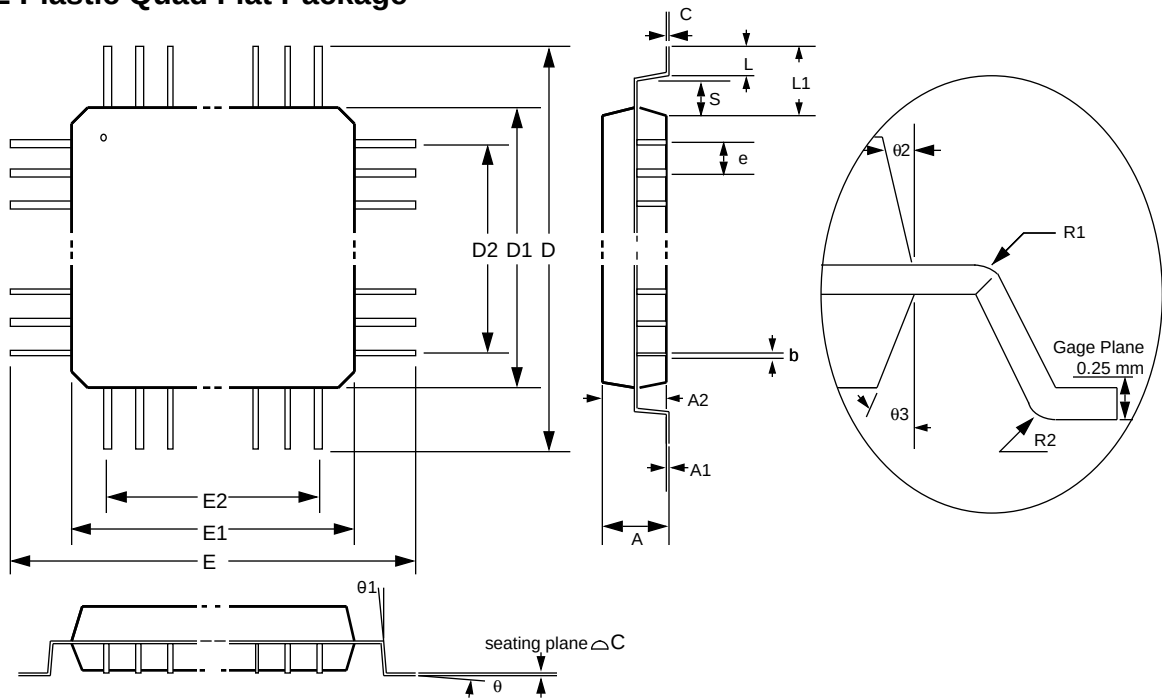
Note:

- 1.Dimension D Max & S include mold flash or tie bar burrs.
- 2.Dimension E1 does not include interlead flash.
- 3.Dimension D & E1 include mold mismatch and are determined at the mold parting line.
- 4.Dimension B1 does not include dambar protrusion/intrusion.
- 5.Controlling dimension is inch.
- 6.General appearance spec. should base on final visual inspection spec.

Symbol	Dimension in Inch	Dimension in mm
	minimal/maximal	minimal/maximal
A	- / 0.210	- / 5.33
A1	0.010 / -	0.25 / -
A2	0.150 / 0.160	3.81 / 4.06
B	0.016 / 0.022	0.41 / 0.56
B1	0.048 / 0.054	1.22 / 1.37
C	0.008 / 0.014	0.20 / 0.36
D	- / 2.070	- / 52.58
E	0.590 / 0.610	14.99 / 15.49
E1	0.540 / 0.552	13.72 / 14.02
e1	0.090 / 0.110	2.29 / 2.79
L	0.120 / 0.140	3.05 / 3.56
E\	0° / 15°	0° / 15°
eA	0.630 / 0.670	16.00 / 17.02
S	/ 0.090	- / 2.29

44L Plastic Leaded Chip Carrier (PLCC)

44L Plastic Quad Flat Package

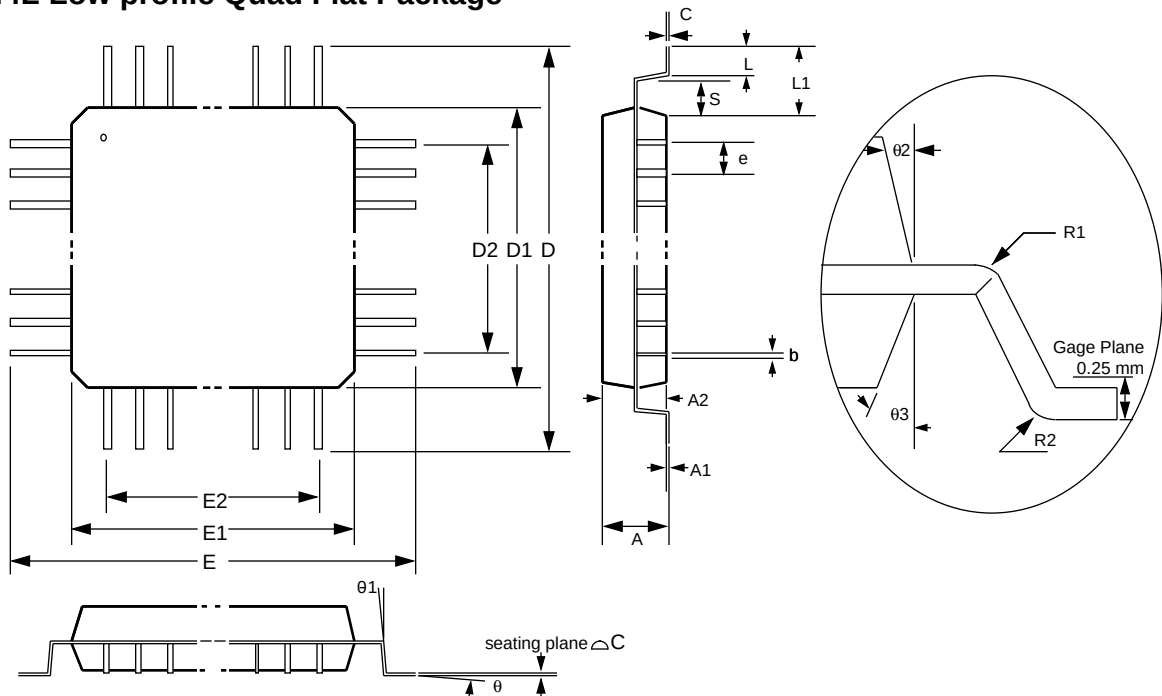


Note:

1. Dimension D1 and E1 do not include mold protrusion. Allowance protrusion is 0.25mm per side. Dimensions D1 and E1 do include mold mismatch and are determined at datum plane.
2. Dimension b does not include dambar protrusion. Allowance dambar protrusion shall be 0.08 mm total in excess of the b dimension at maximum material condition. Dambar cannot be located on the lower radius or the lead foot.

Symbol	Dimension in Inch	Dimension in mm
	minimal/maximal	minimal/maximal
A	- / 0.100	- / 2.55
A1	0.006 / 0.014	0.15 / 0.35
A2	0.071 / 0.087	1.80 / 2.20
b	0.012 / 0.018	0.30 / 0.45
c	0.004 / 0.009	0.09 / 0.20
D	0.520 BSC	13.20 BSC
D1	0.394 BSC	10.00 BSC
D2	0.315	8.00
E	0.520 BSC	13.20 BSC
E1	0.394 BSC	10.00 BSC
E2	0.315	8.00
e	0.031 BSC	0.80 BSC
L	0.029 / 0.041	0.73 / 1.03
L1	0.063	1.60
R1	0.005 / -	0.13 / -
R2	0.005 / 0.012	0.13 / 0.30
S	0.008 / -	0.20 / -
θ	0° / 7°	as left
$\theta1$	0° / -	as left
$\theta2$	10° REF	as left
$\theta3$	7° REF	as left
C	0.004	0.10

44L Low profile Quad Flat Package



Note:

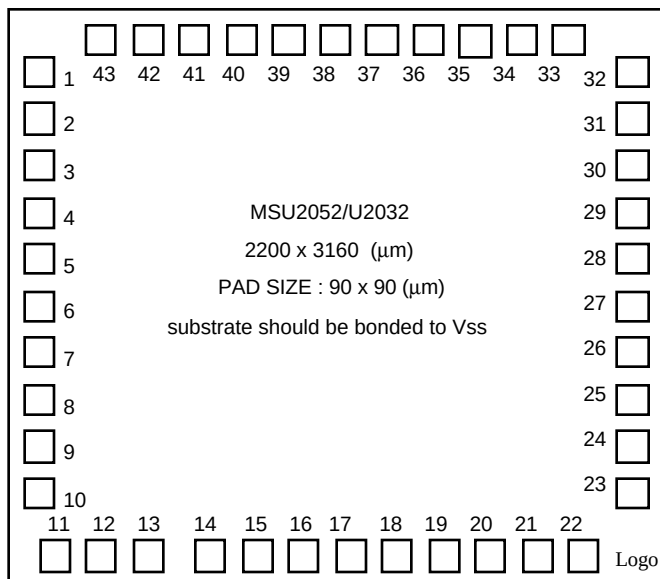
1. Dimension D1 and E1 do not include mold protrusion. Allowance protrusion is 0.25mm per side. D1 and E1 are maximal plastic body size dimensions including mold mismatch.
2. Dimension b does not include dambar protrusion. Allowance dambar protrusion shall not cause the lead width to exceed the maximal b dimension by more than 0.08 mm.
3. Dambar can not be located on the lower radius or the foot. Minimal space between protrusion and an adjacent lead is 0.07 mm for 0.4 mm and 0.5 mm pitch packages.

Symbol	Dimension in Inch	Dimension in mm
	minimal/maximal	minimal/maximal
A	- / 0.063	- / 1.60
A1	0.002 / 0.006	0.05 / 0.15
A2	0.053 / 0.057	1.35 / 1.45
b	0.012 / 0.018	0.30 / 0.45
c	0.004 / 0.008	0.09 / 0.20
D	0.472 BSC	12.00 BSC
D1	0.393 BSC	10.00 BSC
D2	0.315	8.00
E	0.472 BSC	12.00 BSC
E1	0.393 BSC	10.00 BSC
E2	0.315	8.00
e	0.031 BSC	0.80 BSC
L	0.018 / 0.030	0.45 / 0.75
L1	0.039 REF	1.00 REF
R1	0.003 / -	0.08 / -
R2	0.003 / 0.008	0.08 / 0.20
S	0.008 / -	0.20 / -
θ	0° / 7°	as left
θ1	0° / -	as left
θ2	11°/13°	as left
θ3	11°/13°	as left
C	0.004	0.10

Bonding Information

Index	PAD-NAME	X-COORD	Y-COORD
1	P1.5	237	186
2	P1.6	400	186
3	P1.7	559	186
4	RES	722	186
5	P3.0	882	186
6	P3.1	1044	186
7	P3.2	1204	186
8	P3.3	1366	186
9	P3.4	1526	186
10	P3.5	1688	186
11	P3.6	1931	310
12	P3.7	1931	537
13	XTAL2	1931	769
14	XTAL1	1931	1090
15	VSS	1931	1291
16	VSS	1931	1442
17	VSS	1931	1593
18	P2.0	1931	1791
19	P2.1	1931	2016
20	P2.2	1931	2243
21	P2.3	1931	2468
22	P2.4	1931	2696

Index	PAD-NAME	X-COORD	Y-COORD
23	P2.5	1688	2874
24	P2.6	1526	2874
25	P2.7	1366	2874
26	#PSEN	1204	2874
27	ALE	1044	2874
28	#EA	882	2874
29	P0.7	722	2874
30	P0.6	559	2874
31	P0.5	400	2874
32	P0.4	237	2874
33	P0.3	168	2595
34	P0.2	168	2367
35	P0.1	168	2142
36	P0.0	168	1915
37	VDD	168	1717
38	VDD	168	1566
39	P1.0	168	1369
40	P1.1	168	1144
41	P1.2	168	917
42	P1.3	168	692
43	P1.4	168	464



pid 252* 12/96
pid 252** 01/97
pid 252*** 02/97
pid 252A 02/98

To: Mosel Vitelic Inc.
886-3-578-4732 (fax #)
Attn: Sales & Marketing Department

Product Request Form

We hereby request MVI to start producing MSU2052 which is specified below.

Please send us the product code and a hardcopy of data code as well as data code file duplicated on floppy diskette. No further confirmation is necessary.

Production will start automatically once you receive our data code and verify that the checksum is match.

Mass Production of the captioned device shall be done in accordance with the purchase order(s) issued by us or a company specified by us. All terms and conditions are based on the development agreement and/or contract signed between MVI and us.

Data Code Descriptions		IC descriptions	
Code Length		☐ Dice form ☐ P type = 40L-PDIP ☐ J type = 44L-PLCC ☐ Q type = 44L-PQFP ☐ L type = 44L-LQFP	☐ U2052L16, 16 MHz low working voltage ☐ U2052C16, 16 MHz ☐ U2052C25, 25 MHz ☐ U2052C40, 40 MHz
File Length			
File Name			
Checksum			
Unused Data Byte	☐ 00h filled ☐ FFh filled	Top Marking (fill only for packaged) ☐ Use MVI logo, date code and part number ☐ Use my specifications as described below	
Format	☐ HEX format ☐ Binary code format	Specify below fields only for customer top marking Date code location descriptions ☐ Use regular date code as MVI's ☐ Leave it as blank ☐ use right side five letters	
Media	☐ EPROM ☐ 8751 chip ☐ File on Floppy ☐ E-mail file	<div style="display: flex; align-items: center;"> ☐ use right side five letters <div style="margin-left: 20px;"> <input type="text"/> <input type="text"/> <input type="text"/> <input type="text"/> <input type="text"/> </div> </div>	
		Logo Specifications ☐ Leave it blank ☐ Use my specifications as attachment	
		Part number specified, less than 15 digits <div style="display: flex; align-items: center;"> <input type="text"/> <input type="text"/> <input type="text"/> <input type="text"/> <input type="text"/> <input type="text"/> <input type="text"/> <input type="text"/> <input type="text"/> <input type="text"/> <input type="text"/> <input type="text"/> <input type="text"/> <input type="text"/> <input type="text"/> </div>	

Phone # : _____ Fax # : _____

Company Name : _____

Signature : _____

Name (Typed) : _____

Position Title : _____

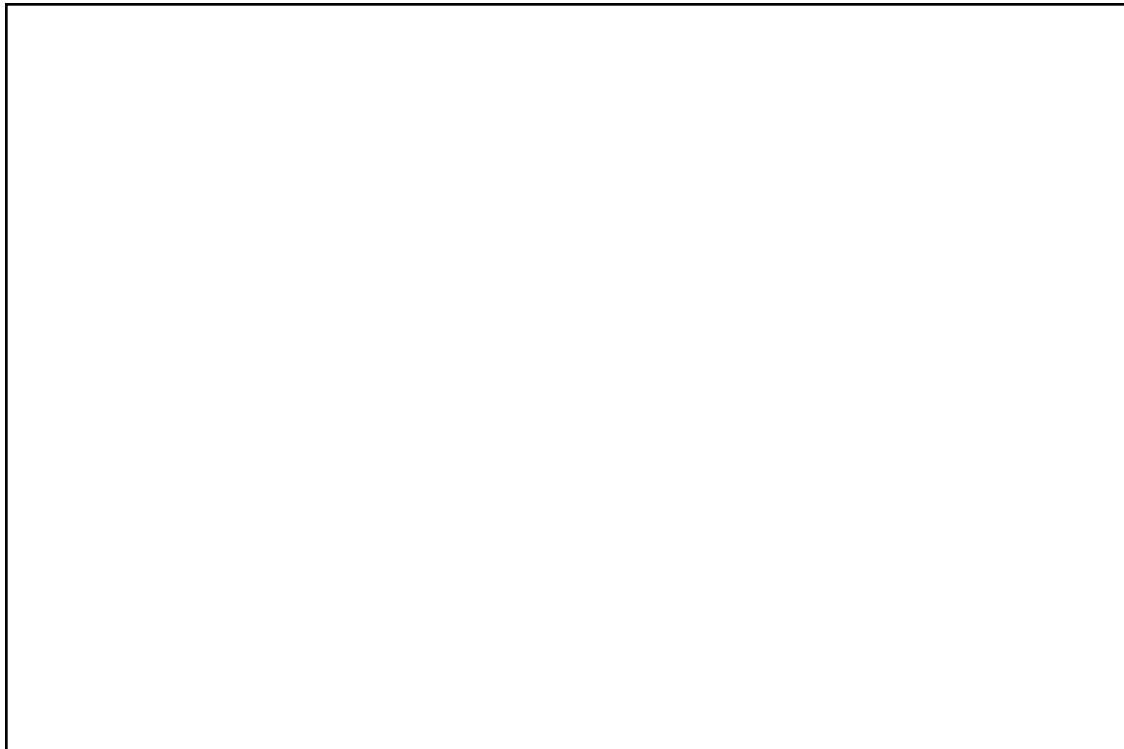
Department, Section : _____

Signature Date : _____

To: Mosel Vitelic Inc.
886-3-578-4732 (fax#)
Attn: Sales & Marketing Department

Logo Top Marking Request & spec.

We hereby request MVI to have our logo printed on top of the device package. Below is the specification of our logo in 20:1 scale base. This logo diagram is clear enough and is able to be shrunk directly to fit into available top marking area described on page.



Phone # : _____ Fax # : _____

Company Name : _____

Signature : _____

Name (Typed) : _____

Position Title : _____

Department, Section : _____

Signature Date : _____

U.S.A.

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FAX: 408-433-0185

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TAIPO, NT, HONG KONG
PHONE: 852-2665-4883
FAX: 852-2664-7535

TAIWAN

7F, NO. 102
MIN-CHUAN E. ROAD, SEC. 3
TAIPEI
PHONE: 886-2-2545-1213
FAX: 886-2-2545-1209

1 CREATION ROAD I
SCIENCE BASED IND. PARK
HSIN CHU, TAIWAN, R.O.C.
PHONE: 886-3-578-3344
FAX: 886-3-579-2838

JAPAN

WBG MARINE WEST 25F
6, NAKASE 2-CHOME
MIHAMA-KU, CHIBA-SHI
CHIBA 261-71
PHONE: 81-43-299-6000
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LONG BEACH, CA 90804
PHONE: 562-498-3314
FAX: 562-597-2174

CENTRAL & SOUTHEASTERN

604 FIELDWOOD CIRCLE
RICHARDSON, TX 75081
PHONE: 972-690-1402
FAX: 972-690-0341

NORTHEASTERN

SUITE 436
20 TRAFALGAR SQUARE
NASHUA, NH 03063
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